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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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## TRIPLE ELEMENT THYRISTOR OVERVOLTAGE PROTECTORS

**BOURNS®**

### TISP7015 (VLV) Overvoltage Protector

#### Three Terminal Very Low Voltage (VLV) Protection

Ion-Implanted Breakdown Region  
- Precise and Stable Voltage

DEVICE	V <sub>DRM</sub> V	V <sub>(BO)</sub> V
'7015	8	15

#### Protection for Signal, Data and Control Lines

- ISDN
- T1/E1
- RS232 & RS485

Low Capacitance ..... 40 pF max.

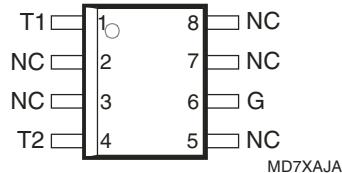
#### Rated for International Surge Wave Shapes

Voltage Waveshape	Standard	I <sub>PPSM</sub> A
8/20	IEC 61000-4-5	150
10/700	ITU-T K.20/45/21	40
10/1000	GR-1089-CORE	30



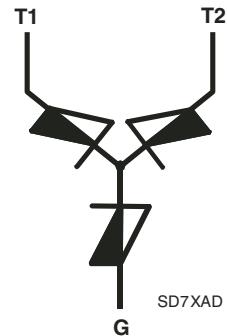
..... UL Recognized Components

#### D Package (Top View)



NC - No internal connection

#### Device Symbol



#### Description

The TISP7015 is a 3-point overvoltage protector designed for protecting against metallic (differential mode) and simultaneous longitudinal (common mode) impulses.

These devices are designed to limit overvoltages between signal, data and control port conductors, connected to terminals T1 and T2, and a protective ground, G. Each terminal pair has a symmetrical voltage-triggered bidirectional thyristor characteristic (Figure 1). Overvoltages are initially clipped by breakdown clamping until the voltage rises to the breakdown level, which causes the device to crowbar into a low-voltage on state. This low-voltage on state causes the current resulting from the overvoltage to be safely diverted through the device. The device switches off when the diverted current falls below the holding current value.

Terminals marked NC do not have any internal connections and may be left floating or tied to some circuit point.

#### How To Order

Device	Package	Carrier	For Standard Termination Finish Order As	For Lead Free Termination Finish Order As
TISP7015	D, Small-outline	Embossed Tape Reeled	TISP7015DR	TISP7015DR-S
		Tube	TISP7015D	TISP7015D-S

\*RoHS Directive 2002/95/EC Jan 27 2003 including Annex

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Specifications are subject to change without notice.

Customers should verify actual device performance in their specific applications.

# TISP7015 (VLV) Overvoltage Protector

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## Absolute Maximum Ratings, $T_J = 25^\circ\text{C}$ (Unless Otherwise Noted)

Rating	Symbol	Value	Unit
Repetitive peak off-state voltage	$V_{\text{DRM}}$	$\pm 8$	V
Non-repetitive peak on-state pulse current (see Notes 1 and 2)	$I_{\text{PPSM}}$	150	A
8/20 (IEC 61000-4-5, clause 7.2, $R = 0$ , combination wave generator)		40	
5/310 (ITU-T recommendation K.44, 10/700 generator used for K.20/45/21)		30	
10/1000 (Telcordia GR-1089-CORE, 10/1000 voltage wave shape)			
Non-repetitive peak on-state current (see Notes 1, 2 and 3)	$I_{\text{TSM}}$	4	A
50/60 Hz, 1 s			
Junction temperature	$T_J$	-40 to +150	°C
Storage temperature range	$T_{\text{stg}}$	-65 to +150	°C

NOTES: 1. Initially, the TISP7015 must be in thermal equilibrium at the specified  $T_A$ . The surge may be repeated after the TISP7015 returns to its initial conditions.  
 2. These non-repetitive rated currents are peak values of either polarity.  
 3. Total return current,  $I_G$ , value.

## Electrical Characteristics, $T_J = 25^\circ\text{C}$ (Unless Otherwise Noted)

Parameter	Test Conditions	Min	Typ	Max	Unit
$I_{\text{DRM}}$	Repetitive peak off-state current $V_D = \pm V_{\text{DRM}}$			$\pm 4$	µA
$V_{(BO)}$	Breakover voltage $dv/dt = \pm 250 \text{ V/ms}$ , $R_{\text{SOURCE}} = 300 \Omega$			$\pm 15$	V
$I_{(BO)}$	Breakover current $dv/dt = \pm 250 \text{ V/ms}$ , $R_{\text{SOURCE}} = 300 \Omega$			$\pm 100$	mA
$V_T$	On-state voltage $I_T = \pm 5 \text{ A}$ , $t_W = 100 \mu\text{s}$			$\pm 4$	V
$I_H$	Holding current $I_T = \pm 5 \text{ A}$ , $di/dt = +/- 30 \text{ mA/ms}$	$\pm 30$			mA
$I_D$	Off-state current $V_D = \pm 0.85V_{\text{DRM}}$ , $T_A = 85^\circ\text{C}$			$\pm 10$	µA
$C_{KA}$	Off-state capacitance $f = 1 \text{ MHz}$ , $V_d = 30 \text{ mV rms}$ , $V_D = 0$ (see Note 4)		32	40	pF

NOTE 4: Three-terminal guarded measurement, unmeasured terminal voltage bias is zero.

## Thermal Characteristics

Parameter	Test Conditions	Min	Typ	Max	Unit
$R_{\theta JA}$	Junction to free air thermal resistance $P_{\text{tot}} = 0.8 \Omega$ , $T_A = 25^\circ\text{C}$ , $5 \text{ cm}^2$ , FR4 PCB			160	°C/W

# TISP7015 (VLV) Overvoltage Protector

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## Parameter Measurement Information

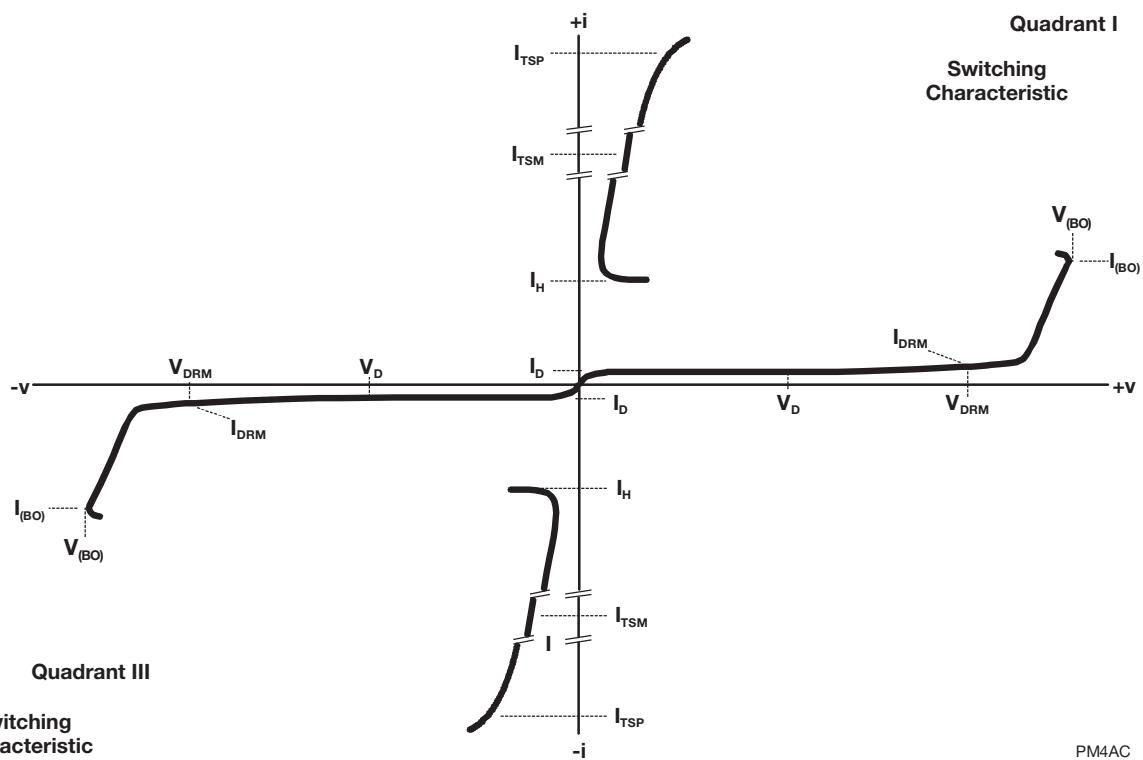


Figure 1. Voltage-Current Characteristic for any Terminal Pair

**MECHANICAL DATA****Device Symbolization Code**

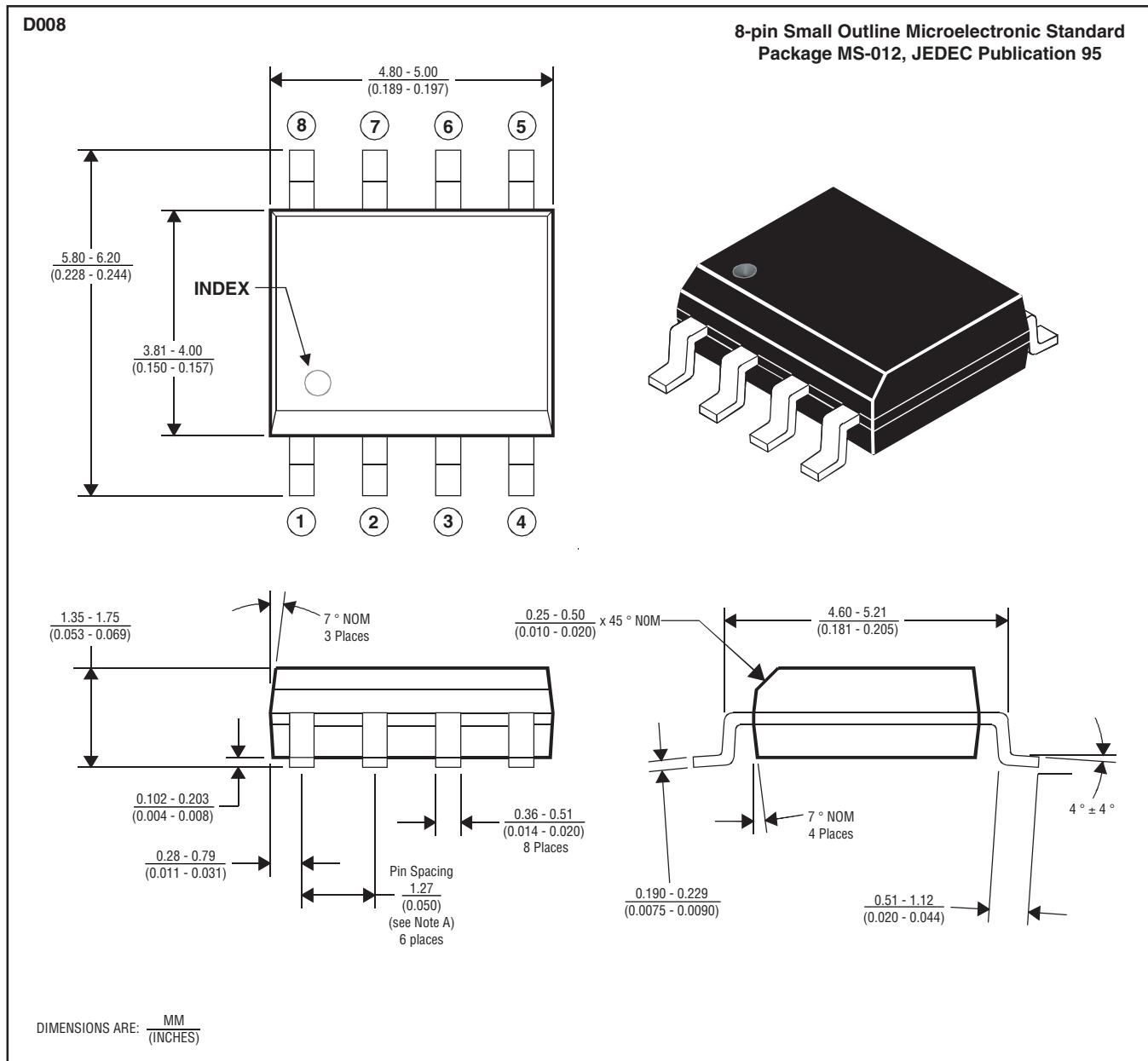
Devices will be coded as below.

Device	Symbolization Code
TISP7015	7015

## MECHANICAL DATA

### D008 Plastic Small-outline Package

This small-outline package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



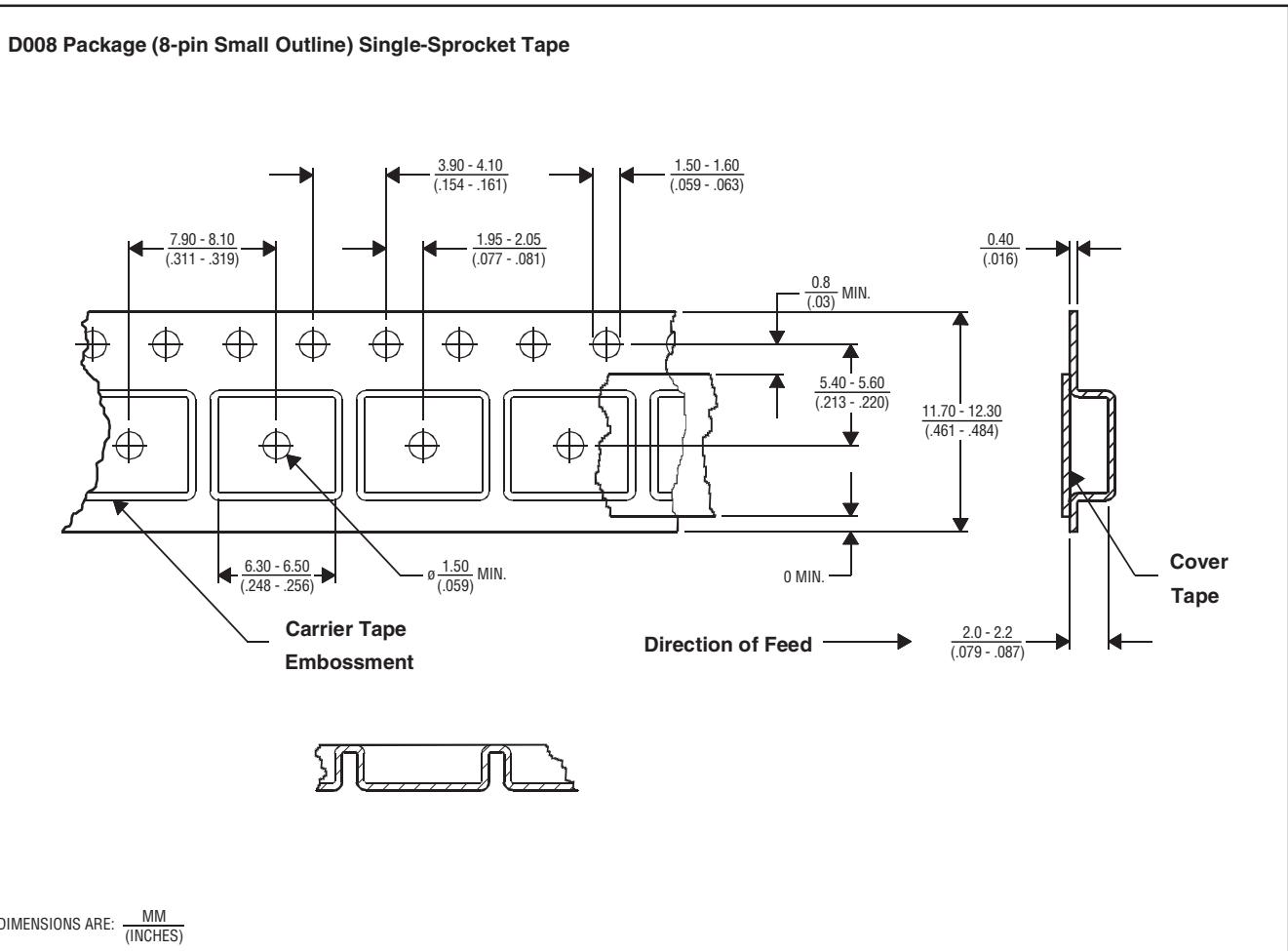
NOTES: A. Leads are within 0.25 (0.010) radius of true position at maximum material condition.  
 B. Body dimensions do not include mold flash or protrusion.  
 C. Mold flash or protrusion shall not exceed 0.15 (0.006).  
 D. Lead tips to be planar within  $\pm 0.051$  (0.002).

MDXXAAE

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## MECHANICAL DATA

## D008 Tape Dimensions



NOTES: A. Taped devices are supplied on a reel of the following dimensions:-

MDXXATC

Reel diameter:  $\frac{330 +0.0/-4.0}{(12.99 +0.0/-157)}$

Reel hub diameter:  $\frac{100 \pm 2.0}{(3.937 \pm .079)}$

Reel axial hole:  $\frac{13.0 \pm 0.2}{(.512 \pm .008)}$

B. 2500 devices are on a reel.

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